Market and Technology Trends of Wafer Level Packages
Santosh Kumar – Senior Product Marketing Manager Yole Developpement

While scaling options remain uncertain in the shorter term and continue to be investigated, the spotlight turns to advanced packages. Emerging packages such as fan-out wafer level packages (FOWLP) and 2.5D/3D IC solutions together with more conventional but upgraded flip chip BGAs aim to bridge the gap and revive the cost/performance curve while at the same time adding more functionality through integration. Recently FOWLP has attracted much attention with new product announcements and strong involvement of some key players, lately most notably TSMC. The presentation will provide an overview of the products announcements, commercialization roadmaps as well as market forecasts per application. Insights and trends into the different fan-out packaging approaches by applications, business models and major players will be reviewed. Additionally fan-in WLP technology and market trends will also be discussed briefly.

Organized by: